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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	F ² MC-16FX
Core Size	16-Bit
Speed	32MHz
Connectivity	CANbus, I ² C, LINbus, SCI, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	52
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 21x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb96f622rbpmc1-gse1

■ A/D converter

- SAR-type
- 8/10-bit resolution
- Signals interrupt on conversion end, single conversion mode, continuous conversion mode, stop conversion mode, activation by software, external trigger, reload timers and PPGs
- Range Comparator Function

■ Source Clock Timers

Three independent clock timers (23-bit RC clock timer, 23-bit Main clock timer, 17-bit Sub clock timer)

■ Hardware Watchdog Timer

- Hardware watchdog timer is active after reset
- Window function of Watchdog Timer is used to select the lower window limit of the watchdog interval

■ Reload Timers

- 16-bit wide
- Prescaler with $1/2^1$, $1/2^2$, $1/2^3$, $1/2^4$, $1/2^5$, $1/2^6$ of peripheral clock frequency
- Event count function

■ Free-Running Timers

- Signals an interrupt on overflow, supports timer clear upon match with Output Compare (0, 4)
- Prescaler with 1, $1/2^1$, $1/2^2$, $1/2^3$, $1/2^4$, $1/2^5$, $1/2^6$, $1/2^7$, $1/2^8$ of peripheral clock frequency

■ Input Capture Units

- 16-bit wide
- Signals an interrupt upon external event
- Rising edge, Falling edge or Both (rising & falling) edges sensitive

■ Output Compare Units

- 16-bit wide
- Signals an interrupt when a match with Free-running Timer occurs
- A pair of compare registers can be used to generate an output signal

■ Programmable Pulse Generator

- 16-bit down counter, cycle and duty setting registers
- Can be used as 2×8 -bit PPG
- Interrupt at trigger, counter borrow and/or duty match
- PWM operation and one-shot operation
- Internal prescaler allows 1, $1/4$, $1/16$, $1/64$ of peripheral clock as counter clock or of selected Reload timer underflow as clock input
- Can be triggered by software or reload timer
- Can trigger ADC conversion
- Timing point capture

■ Quadrature Position/Revolution Counter (QPRC)

- Up/down count mode, Phase difference count mode, Count mode with direction
- 16-bit position counter
- 16-bit revolution counter
- Two 16-bit compare registers with interrupt
- Detection edge of the three external event input pins AIN, BIN and ZIN is configurable

■ Real Time Clock

- Operational on main oscillation (4MHz), sub oscillation (32kHz) or RC oscillation (100kHz/2MHz)
- Capable to correct oscillation deviation of Sub clock or RC oscillator clock (clock calibration)
- Read/write accessible second/minute/hour registers
- Can signal interrupts every half second/second/minute/hour/day
- Internal clock divider and prescaler provide exact 1s clock

■ External Interrupts

- Edge or Level sensitive
- Interrupt mask bit per channel
- Each available CAN channel RX has an external interrupt for wake-up
- Selected USART channels SIN have an external interrupt for wake-up

■ Non Maskable Interrupt

- Disabled after reset, can be enabled by Boot-ROM depending on ROM configuration block
- Once enabled, can not be disabled other than by reset
- High or Low level sensitive
- Pin shared with external interrupt 0

■ I/O Ports

- Most of the external pins can be used as general purpose I/O
- All push-pull outputs (except when used as I²C SDA/SCL line)
- Bit-wise programmable as input/output or peripheral signal
- Bit-wise programmable input enable
- One input level per GPIO-pin (either Automotive or CMOS hysteresis)
- Bit-wise programmable pull-up resistor

■ Built-in On Chip Debugger (OCD)

- One-wire debug tool interface
- Break function:
 - Hardware break: 6 points (shared with code event)
 - Software break: 4096 points
- Event function
 - Code event: 6 points (shared with hardware break)
 - Data event: 6 points
 - Event sequencer: 2 levels + reset
- Execution time measurement function
- Trace function: 42 branches
- Security function

■ Flash Memory

- Dual operation flash allowing reading of one Flash bank while programming or erasing the other bank
- Command sequencer for automatic execution of programming algorithm and for supporting DMA for programming of the Flash Memory
- Supports automatic programming, Embedded Algorithm
- Write/Erase/Erase-Suspend/Resume commands
- A flag indicating completion of the automatic algorithm
- Erase can be performed on each sector individually
- Sector protection
- Flash Security feature to protect the content of the Flash
- Low voltage detection during Flash erase or write

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1. Product Lineup

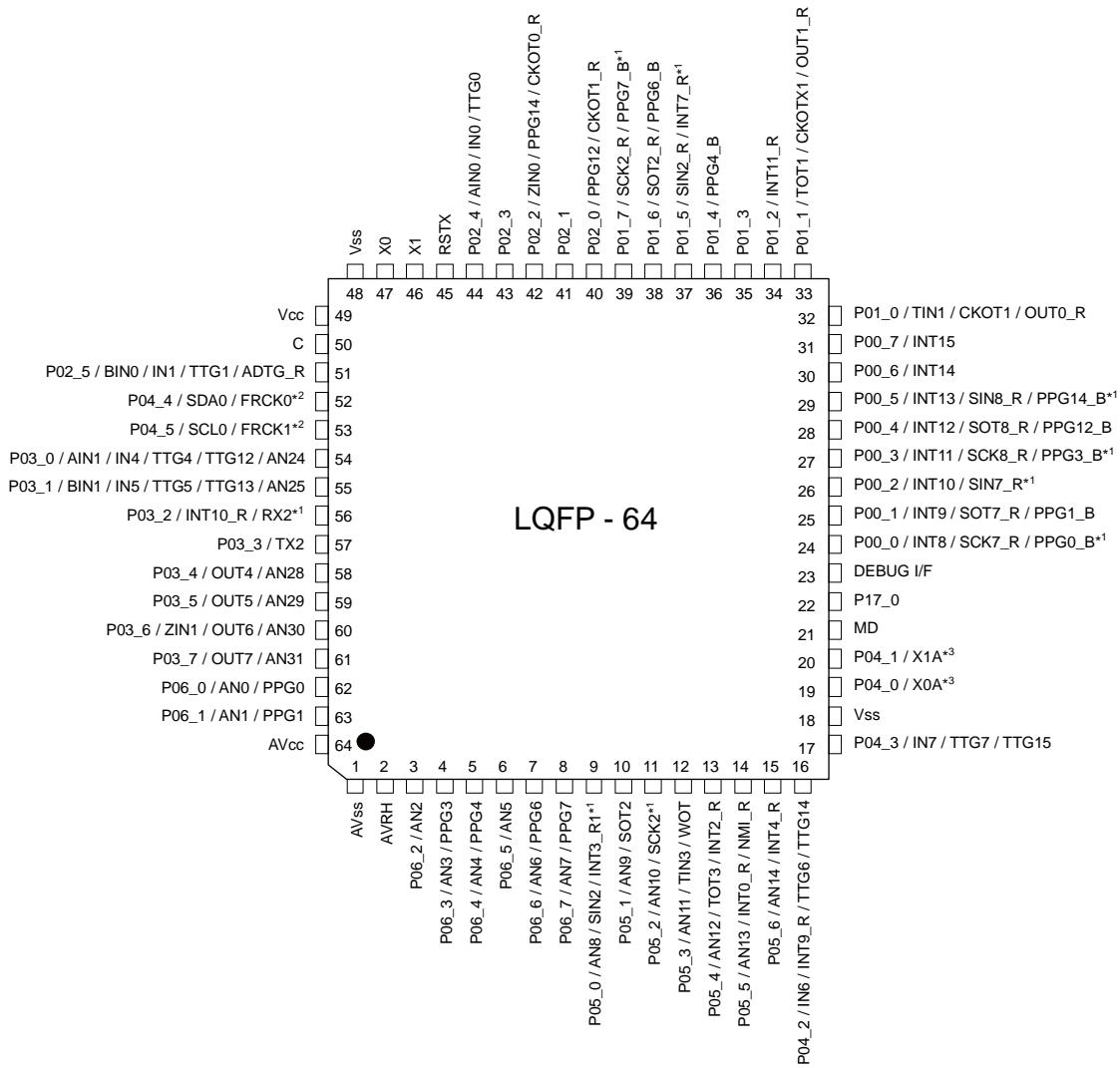
Features		MB96620	Remark
Product Type		Flash Memory Product	
Subclock		Subclock can be set by software	
Dual Operation Flash Memory	RAM	-	Product Options R: MCU with CAN A: MCU without CAN
32.5KB + 32KB	4KB	MB96F622R, MB96F622A	
64.5KB + 32KB	10KB	MB96F623R, MB96F623A	
128.5KB + 32KB	10KB	MB96F625R, MB96F625A	
Package	LQFP-64 FPT-64P-M23/M24		
DMA	2ch		
USART	3ch		LIN-USART 2/7/8
with automatic LIN-Header transmission/reception	Yes (only 1ch)		LIN-USART 2
	No		
I ² C	1ch	I ² C 0	
8/10-bit A/D Converter	21ch	AN 0 to 14/24/25/28 to 31	
with Data Buffer	No		
	Yes		
	No		
	No		
16-bit Reload Timer (RLT)	3ch	RLT 1/3/6	
16-bit Free-Running Timer (FRT)	4ch	FRT 0 to 3 FRT 2/3 does not have external clock input pin	
16-bit Input Capture Unit (ICU)	8ch (2 channels for LIN-USART)	ICU 0/1/4 to 7/9/10 (ICU 9/10 for LIN-USART)	
16-bit Output Compare Unit (OCU)	6ch	OCU 0/1/4 to 7	
8/16-bit Programmable Pulse Generator (PPG)	8ch (16-bit) / 16ch (8-bit)	PPG 0/1/3/4/6/7/12/14	
with Timing point capture	Yes		
	No		
	No		
Quadrature Position/Revolution Counter (QPRC)	2ch	QPRC 0/1	
CAN Interface	1ch	CAN 2 32 Message Buffers	
External Interrupts (INT)	13ch	INT 0/2/3/4/7 to 15	
Non-Maskable Interrupt (NMI)	1ch		
Real Time Clock (RTC)	1ch		
I/O Ports	50 (Dual clock mode) 52 (Single clock mode)		
Clock Calibration Unit (CAL)	1ch		
Clock Output Function	2ch		
Low Voltage Detection Function	Yes	Low voltage detection function can be disabled by software	
Hardware Watchdog Timer	Yes		
On-chip RC-oscillator	Yes		
On-chip Debugger	Yes		

Note:

All signals of the peripheral function in each product cannot be allocated by limiting the pins of package.
It is necessary to use the port relocate function of the general I/O port according to your function use.

3. Pin Assignment

(Top view)



(FPT-64P-M23/M24)

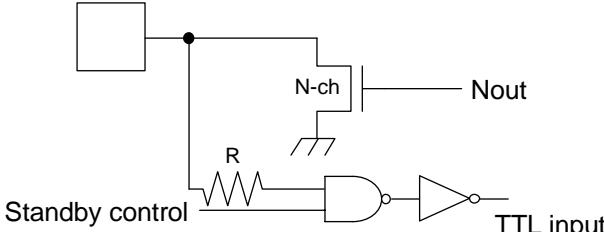
*1: CMOS input level only

*2: CMOS input level only for I²C

*3: Please set ROM Configuration Block (RCB) to use the subclock.

Other than those above, general-purpose pins have only Automotive input level.

Pin name	Feature	Description
WOT	RTC	Real Time clock output pin
X0	Clock	Oscillator input pin
X0A	Clock	Subclock Oscillator input pin
X1	Clock	Oscillator output pin
X1A	Clock	Subclock Oscillator output pin
ZINn	QPRC	Quadrature Position/Revolution Counter Unit n input pin

Type	Circuit	Remarks
O	 <p>Standby control for input shutdown</p>	<ul style="list-style-type: none"> • Open-drain I/O • Output 25mA, Vcc = 2.7V • TTL input

8. RAMSTART Addresses

Devices	Bank 0 RAM size	RAMSTART0
MB96F622	4KB	00:7200H
MB96F623	10KB	00:5A00H
MB96F625		

9. User ROM Memory Map For Flash Devices

		MB96F622	MB96F623	MB96F625	
CPU mode address	Flash memory mode address	Flash size 32.5KB + 32KB	Flash size 64.5KB + 32KB	Flash size 128.5KB + 32KB	
FF:FFFF _H	3F:FFFF _H	SA39 - 32KB		SA39 - 64KB	
FF:8000 _H	3F:8000 _H				
FF:7FFF _H	3F:7FFF _H				
FF:0000 _H	3F:0000 _H				
FE:FFFF _H	3E:FFFF _H				
FE:0000 _H	3E:0000 _H			SA38 - 64KB	
FD:FFFF _H					
DF:A000 _H		Reserved	Reserved	Reserved	
DF:9FFF _H	1F:9FFF _H	SA4 - 8KB		SA4 - 8KB	
DF:8000 _H	1F:8000 _H				
DF:7FFF _H	1F:7FFF _H	SA3 - 8KB		SA3 - 8KB	
DF:6000 _H	1F:6000 _H				
DF:5FFF _H	1F:5FFF _H	SA2 - 8KB		SA2 - 8KB	
DF:4000 _H	1F:4000 _H				
DF:3FFF _H	1F:3FFF _H	SA1 - 8KB		SA1 - 8KB	
DF:2000 _H	1F:2000 _H				
DF:1FFF _H	1F:1FFF _H	SAS - 512B*		SAS - 512B*	
DF:0000 _H	1F:0000 _H				
DE:FFFF _H		Reserved	Reserved	Reserved	
DE:0000 _H					

Bank A of Flash A

Bank B of Flash A

Bank A of Flash A

*: Physical address area of SAS-512B is from DF:0000_H to DF:01FF_H.

Others (from DF:0200_H to DF:1FFF_H) is mirror area of SAS-512B.

Sector SAS contains the ROM configuration block RCBA at CPU address DF:0000_H -DF:01FF_H.

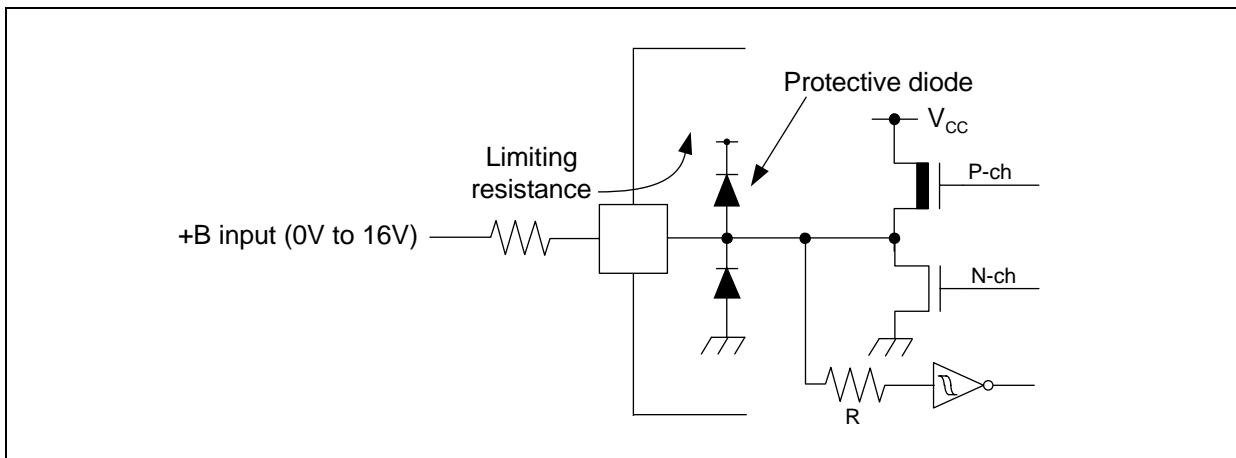
SAS can not be used for E²PROM emulation.

11. Interrupt Vector Table

Vector number	Offset in vector table	Vector name	Cleared by DMA	Index in ICR to program	Description
0	3FC _H	CALLV0	No	-	CALLV instruction
1	3F8 _H	CALLV1	No	-	CALLV instruction
2	3F4 _H	CALLV2	No	-	CALLV instruction
3	3F0 _H	CALLV3	No	-	CALLV instruction
4	3EC _H	CALLV4	No	-	CALLV instruction
5	3E8 _H	CALLV5	No	-	CALLV instruction
6	3E4 _H	CALLV6	No	-	CALLV instruction
7	3E0 _H	CALLV7	No	-	CALLV instruction
8	3DC _H	RESET	No	-	Reset vector
9	3D8 _H	INT9	No	-	INT9 instruction
10	3D4 _H	EXCEPTION	No	-	Undefined instruction execution
11	3D0 _H	NMI	No	-	Non-Maskable Interrupt
12	3CC _H	DLY	No	12	Delayed Interrupt
13	3C8 _H	RC_TIMER	No	13	RC Clock Timer
14	3C4 _H	MC_TIMER	No	14	Main Clock Timer
15	3C0 _H	SC_TIMER	No	15	Sub Clock Timer
16	3BC _H	LVDI	No	16	Low Voltage Detector
17	3B8 _H	EXTINT0	Yes	17	External Interrupt 0
18	3B4 _H	-	-	18	Reserved
19	3B0 _H	EXTINT2	Yes	19	External Interrupt 2
20	3AC _H	EXTINT3	Yes	20	External Interrupt 3
21	3A8 _H	EXTINT4	Yes	21	External Interrupt 4
22	3A4 _H	-	-	22	Reserved
23	3A0 _H	-	-	23	Reserved
24	39C _H	EXTINT7	Yes	24	External Interrupt 7
25	398 _H	EXTINT8	Yes	25	External Interrupt 8
26	394 _H	EXTINT9	Yes	26	External Interrupt 9
27	390 _H	EXTINT10	Yes	27	External Interrupt 10
28	38C _H	EXTINT11	Yes	28	External Interrupt 11
29	388 _H	EXTINT12	Yes	29	External Interrupt 12
30	384 _H	EXTINT13	Yes	30	External Interrupt 13
31	380 _H	EXTINT14	Yes	31	External Interrupt 14
32	37C _H	EXTINT15	Yes	32	External Interrupt 15
33	378 _H	-	-	33	Reserved
34	374 _H	-	-	34	Reserved
35	370 _H	CAN2	No	35	CAN Controller 2
36	36C _H	-	-	36	Reserved
37	368 _H	-	-	37	Reserved
38	364 _H	PPG0	Yes	38	Programmable Pulse Generator 0
39	360 _H	PPG1	Yes	39	Programmable Pulse Generator 1

Vector number	Offset in vector table	Vector name	Cleared by DMA	Index in ICR to program	Description
81	2B8H	OCU4	Yes	81	Output Compare Unit 4
82	2B4H	OCU5	Yes	82	Output Compare Unit 5
83	2B0H	OCU6	Yes	83	Output Compare Unit 6
84	2ACH	OCU7	Yes	84	Output Compare Unit 7
85	2A8H	-	-	85	Reserved
86	2A4H	-	-	86	Reserved
87	2A0H	-	-	87	Reserved
88	29CH	-	-	88	Reserved
89	298H	FRT0	Yes	89	Free-Running Timer 0
90	294H	FRT1	Yes	90	Free-Running Timer 1
91	290H	FRT2	Yes	91	Free-Running Timer 2
92	28CH	FRT3	Yes	92	Free-Running Timer 3
93	288H	RTC0	No	93	Real Time Clock
94	284H	CAL0	No	94	Clock Calibration Unit
95	280H	-	-	95	Reserved
96	27CH	IIC0	Yes	96	I ² C interface 0
97	278H	-	-	97	Reserved
98	274H	ADC0	Yes	98	A/D Converter 0
99	270H	-	-	99	Reserved
100	26CH	-	-	100	Reserved
101	268H	-	-	101	Reserved
102	264H	-	-	102	Reserved
103	260H	-	-	103	Reserved
104	25CH	-	-	104	Reserved
105	258H	LINR2	Yes	105	LIN USART 2 RX
106	254H	LINT2	Yes	106	LIN USART 2 TX
107	250H	-	-	107	Reserved
108	24CH	-	-	108	Reserved
109	248H	-	-	109	Reserved
110	244H	-	-	110	Reserved
111	240H	-	-	111	Reserved
112	23CH	-	-	112	Reserved
113	238H	-	-	113	Reserved
114	234H	-	-	114	Reserved
115	230H	LINR7	Yes	115	LIN USART 7 RX
116	22CH	LINT7	Yes	116	LIN USART 7 TX
117	228H	LINR8	Yes	117	LIN USART 8 RX
118	224H	LINT8	Yes	118	LIN USART 8 TX
119	220H	-	-	119	Reserved
120	21CH	-	-	120	Reserved
121	218H	-	-	121	Reserved
122	214H	-	-	122	Reserved

- The DEBUG I/F pin has only a protective diode against V_{SS}. Hence it is only permitted to input a negative clamping current (4mA). For protection against positive input voltages, use an external clamping diode which limits the input voltage to maximum 6.0V.
- Sample recommended circuits:



*⁵: The maximum permitted power dissipation depends on the ambient temperature, the air flow velocity and the thermal conductance of the package on the PCB.

The actual power dissipation depends on the customer application and can be calculated as follows:

$$P_D = P_{IO} + P_{INT}$$

$P_{IO} = \sum (V_{OL} \times I_{OL} + V_{OH} \times I_{OH})$ (I/O load power dissipation, sum is performed on all I/O ports)

$$P_{INT} = V_{CC} \times (I_{CC} + I_A)$$
 (internal power dissipation)

I_{CC} is the total core current consumption into V_{CC} as described in the "DC characteristics" and depends on the selected operation mode and clock frequency and the usage of functions like Flash programming.

I_A is the analog current consumption into AV_{CC} .

*⁶: Worst case value for a package mounted on single layer PCB at specified T_A without air flow.

*⁷: Write/erase to a large sector in flash memory is warranted with $TA \leq +105^{\circ}\text{C}$.

WARNING

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

14.2 Recommended Operating Conditions

($V_{SS} = AV_{SS} = 0V$)

Parameter	Symbol	Value			Unit	Remarks
		Min	Typ	Max		
Power supply voltage	V_{CC}, AV_{CC}	2.7	-	5.5	V	
		2.0	-	5.5	V	Maintains RAM data in stop mode
Smoothing capacitor at C pin	C_S	0.5	1.0 to 3.9	4.7	μF	1.0 μF (Allowance within $\pm 50\%$) 3.9 μF (Allowance within $\pm 20\%$) Please use the ceramic capacitor or the capacitor of the frequency response of this level. The smoothing capacitor at V_{CC} must use the one of a capacity value that is larger than C_S .

WARNING

The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure. No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks	
				Min	Typ	Max			
Power supply current in Timer modes ^{*2}	I _{CCTPLL}	V _{CC}	PLL Timer mode with CLKPLL = 32MHz (CLKRC and CLKSC stopped)	-	1800	2245	µA	T _A = +25°C	
				-	-	3165	µA	T _A = +105°C	
				-	-	3975	µA	T _A = +125°C	
	I _{CCTMAIN}		Main Timer mode with CLKMC = 4MHz, SMCR:LPMSS = 0 (CLKPLL, CLKRC and CLKSC stopped)	-	285	325	µA	T _A = +25°C	
				-	-	1085	µA	T _A = +105°C	
				-	-	1930	µA	T _A = +125°C	
	I _{CCTRCH}		RC Timer mode with CLKRC = 2MHz, SMCR:LPMSS = 0 (CLKPLL, CLKMC and CLKSC stopped)	-	160	210	µA	T _A = +25°C	
				-	-	1025	µA	T _A = +105°C	
				-	-	1840	µA	T _A = +125°C	
	I _{CCTRCL}		RC Timer mode with CLKRC = 100kHz (CLKPLL, CLKMC and CLKSC stopped)	-	35	75	µA	T _A = +25°C	
				-	-	855	µA	T _A = +105°C	
				-	-	1640	µA	T _A = +125°C	
	I _{CCTSUB}		Sub Timer mode with CLKSC = 32kHz (CLKMC, CLKPLL and CLKRC stopped)	-	25	65	µA	T _A = +25°C	
				-	-	830	µA	T _A = +105°C	
				-	-	1620	µA	T _A = +125°C	

14.3.2 Pin Characteristics
 $(V_{CC} = AV_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = AV_{SS} = 0V, T_A = -40^\circ C \text{ to } +125^\circ C)$

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
"H" level input voltage	V_{IH}	Port inputs Pnn_m	-	$V_{CC} \times 0.7$	-	$V_{CC} + 0.3$	V	CMOS Hysteresis input
			-	$V_{CC} \times 0.8$	-	$V_{CC} + 0.3$	V	AUTOMOTIVE Hysteresis input
	V_{IHX0S}	X0	External clock in "Fast Clock Input mode"	$VD \times 0.8$	-	VD	V	$VD=1.8V \pm 0.15V$
	V_{IHX0AS}	X0A	External clock in "Oscillation mode"	$V_{CC} \times 0.8$	-	$V_{CC} + 0.3$	V	
	V_{IHR}	RSTX	-	$V_{CC} \times 0.8$	-	$V_{CC} + 0.3$	V	CMOS Hysteresis input
	V_{IHM}	MD	-	$V_{CC} - 0.3$	-	$V_{CC} + 0.3$	V	CMOS Hysteresis input
"L" level input voltage	V_{IL}	Port inputs Pnn_m	-	$V_{SS} - 0.3$	-	$V_{CC} \times 0.3$	V	CMOS Hysteresis input
			-	$V_{SS} - 0.3$	-	$V_{CC} \times 0.5$	V	AUTOMOTIVE Hysteresis input
	V_{ILX0S}	X0	External clock in "Fast Clock Input mode"	V_{SS}	-	$VD \times 0.2$	V	$VD=1.8V \pm 0.15V$
	V_{ILX0AS}	X0A	External clock in "Oscillation mode"	$V_{SS} - 0.3$	-	$V_{CC} \times 0.2$	V	
	V_{ILR}	RSTX	-	$V_{SS} - 0.3$	-	$V_{CC} \times 0.2$	V	CMOS Hysteresis input
	V_{ILM}	MD	-	$V_{SS} - 0.3$	-	$V_{SS} + 0.3$	V	CMOS Hysteresis input
	V_{ILD}	DEBUG I/F	-	$V_{SS} - 0.3$	-	0.8	V	TTL Input

14.4.3 Built-in RC Oscillation Characteristics
 $(V_{CC} = AV_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = AV_{SS} = 0V, T_A = -40^\circ C \text{ to } +125^\circ C)$

Parameter	Symbol	Value			Unit	Remarks
		Min	Typ	Max		
Clock frequency	f_{RC}	50	100	200	kHz	When using slow frequency of RC oscillator
		1	2	4	MHz	When using fast frequency of RC oscillator
RC clock stabilization time	t_{RCSTAB}	80	160	320	μs	When using slow frequency of RC oscillator (16 RC clock cycles)
		64	128	256	μs	When using fast frequency of RC oscillator (256 RC clock cycles)

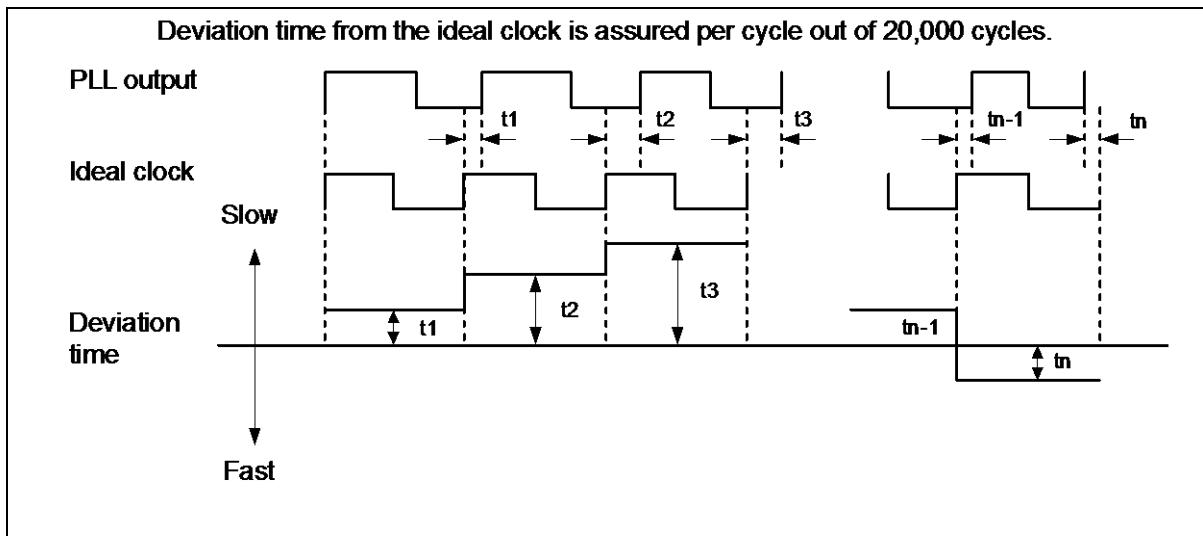
14.4.4 Internal Clock Timing
 $(V_{CC} = AV_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = AV_{SS} = 0V, T_A = -40^\circ C \text{ to } +125^\circ C)$

Parameter	Symbol	Value		Unit
		Min	Max	
Internal System clock frequency (CLKS1 and CLKS2)	f_{CLKS1}, f_{CLKS2}	-	54	MHz
Internal CPU clock frequency (CLKB), Internal peripheral clock frequency (CLKP1)	f_{CLKB}, f_{CLKP1}	-	32	MHz
Internal peripheral clock frequency (CLKP2)	f_{CLKP2}	-	32	MHz

14.4.5 Operating Conditions of PLL

($V_{CC} = AV_{CC} = 2.7V$ to $5.5V$, $V_{SS} = AV_{SS} = 0V$, $T_A = -40^\circ C$ to $+125^\circ C$)

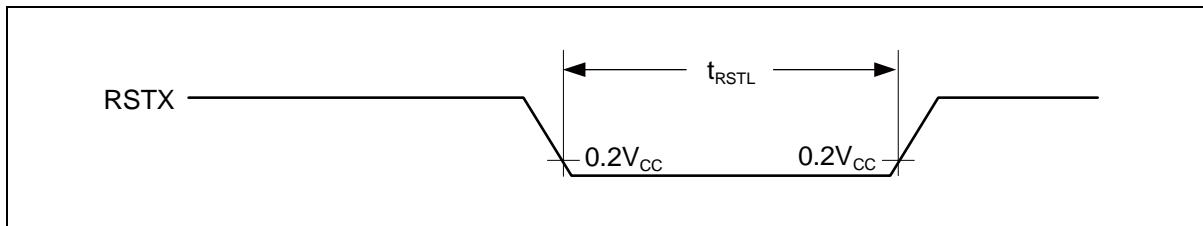
Parameter	Symbol	Value			Unit	Remarks
		Min	Typ	Max		
PLL oscillation stabilization wait time	t_{LOCK}	1	-	4	ms	For CLKMC = 4MHz
PLL input clock frequency	f_{PLL}	4	-	8	MHz	
PLL oscillation clock frequency	f_{CLKVCO}	56	-	108	MHz	Permitted VCO output frequency of PLL (CLKVCO)
PLL phase jitter	t_{PSKew}	-5	-	+5	ns	For CLKMC (PLL input clock) ≥ 4 MHz



14.4.6 Reset Input

($V_{CC} = AV_{CC} = 2.7V$ to $5.5V$, $V_{SS} = AV_{SS} = 0V$, $T_A = -40^\circ C$ to $+125^\circ C$)

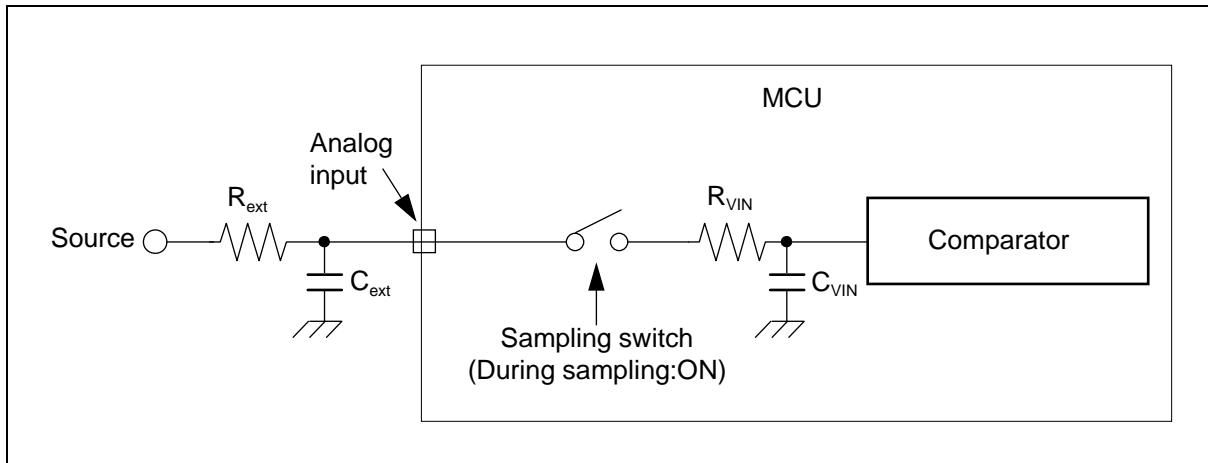
Parameter	Symbol	Pin name	Value		Unit
			Min	Max	
Reset input time	t_{RSTL}	RSTX	10	-	μs
Rejection of reset input time			1	-	μs



14.5.2 Accuracy and Setting of the A/D Converter Sampling Time

If the external impedance is too high or the sampling time too short, the analog voltage charged to the internal sample and hold capacitor is insufficient, adversely affecting the A/D conversion precision.

To satisfy the A/D conversion precision, a sufficient sampling time must be selected. The required sampling time (T_{samp}) depends on the external driving impedance R_{ext} , the board capacitance of the A/D converter input pin C_{ext} and the AV_{CC} voltage level. The following replacement model can be used for the calculation:



R_{ext} : External driving impedance

C_{ext} : Capacitance of PCB at A/D converter input

C_{VIN} : Analog input capacity (I/O, analog switch and ADC are contained)

R_{VIN} : Analog input impedance (I/O, analog switch and ADC are contained)

The following approximation formula for the replacement model above can be used:

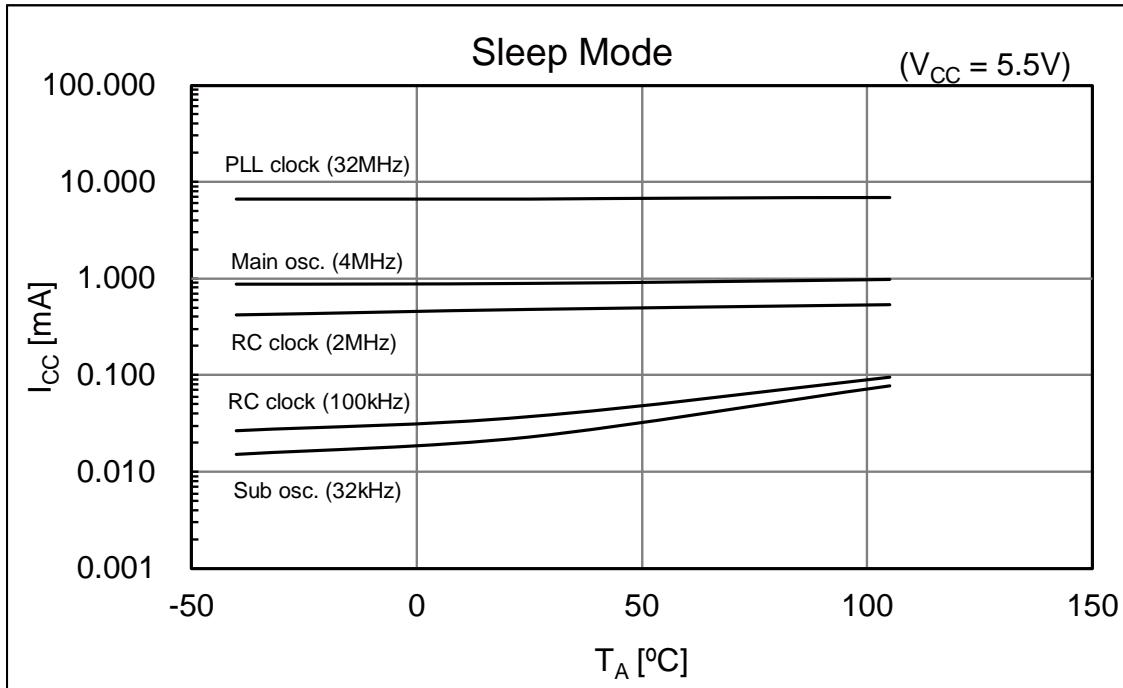
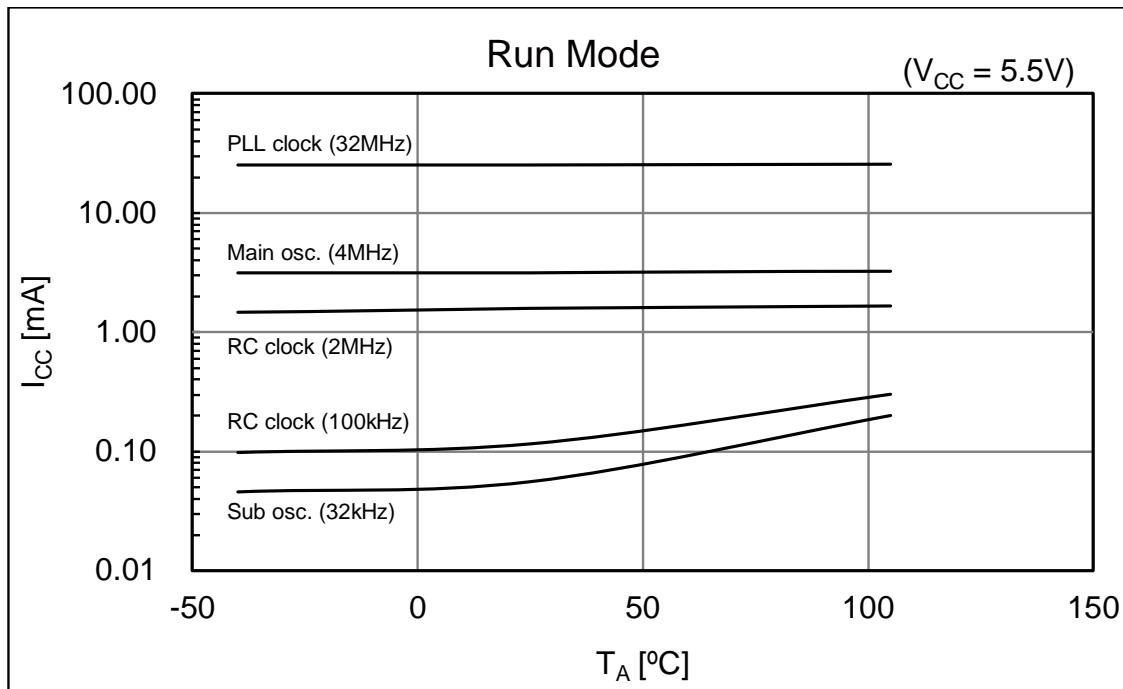
$$T_{\text{samp}} = 7.62 \times (R_{\text{ext}} \times C_{\text{ext}} + (R_{\text{ext}} + R_{\text{VIN}}) \times C_{\text{VIN}})$$

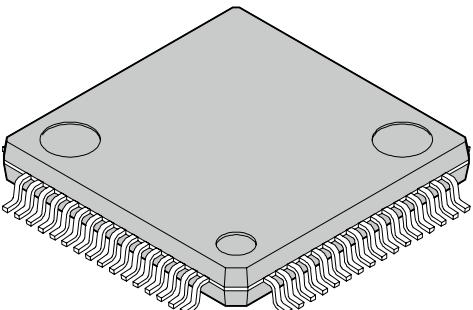
- Do not select a sampling time below the absolute minimum permitted value.
($0.5\mu\text{s}$ for $4.5V \leq AV_{\text{CC}} \leq 5.5V$, $1.2\mu\text{s}$ for $2.7V \leq AV_{\text{CC}} < 4.5V$)
- If the sampling time cannot be sufficient, connect a capacitor of about $0.1\mu\text{F}$ to the analog input pin.
- A big external driving impedance also adversely affects the A/D conversion precision due to the pin input leakage current I_{IL} (static current before the sampling switch) or the analog input leakage current I_{AIN} (total leakage current of pin input and comparator during sampling). The effect of the pin input leakage current I_{IL} cannot be compensated by an external capacitor.
- The accuracy gets worse as $|AV_{\text{RH}} - AV_{\text{SS}}|$ becomes smaller.

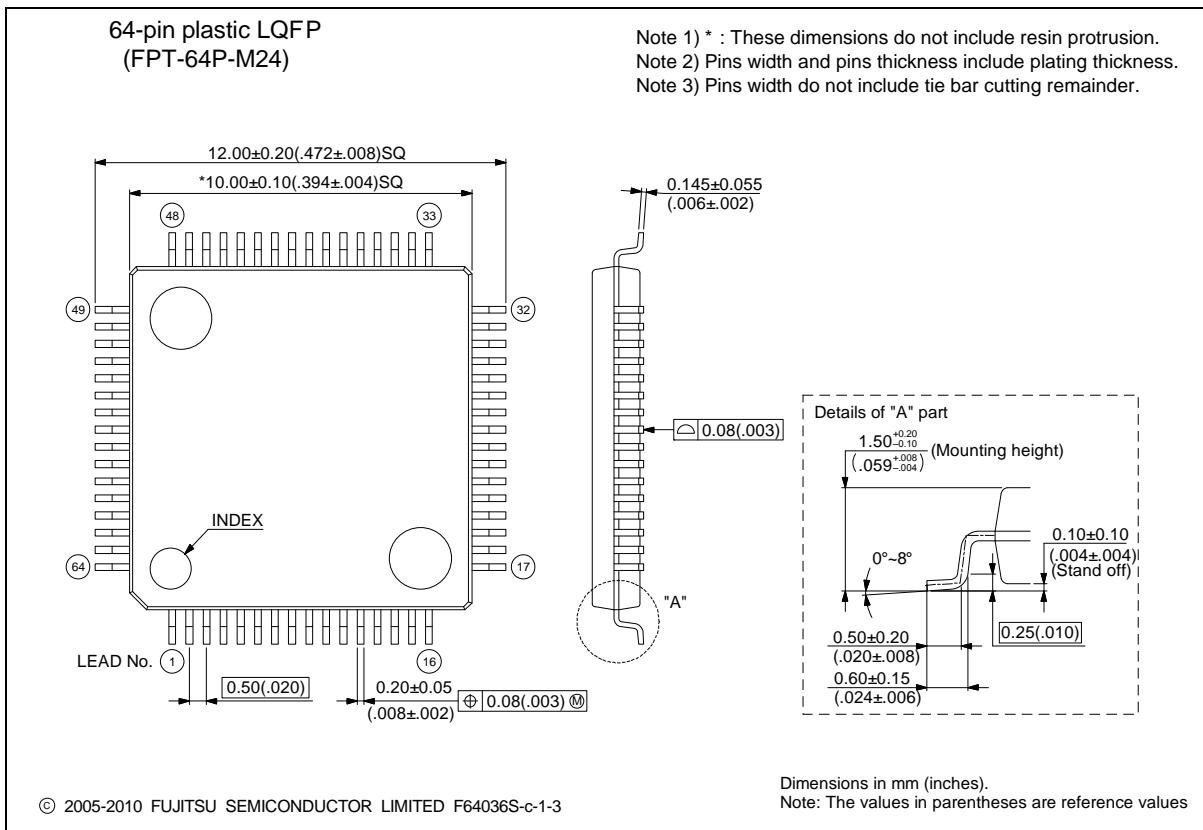
15. Example Characteristics

This characteristic is an actual value of the arbitrary sample. It is not the guaranteed value.

■MB96F625



64-pin plastic LQFP  (FPT-64P-M24)	<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="padding: 5px;">Lead pitch</td><td style="padding: 5px;">0.50 mm</td></tr> <tr> <td style="padding: 5px;">Package width × package length</td><td style="padding: 5px;">10.0 × 10.0 mm</td></tr> <tr> <td style="padding: 5px;">Lead shape</td><td style="padding: 5px;">Gullwing</td></tr> <tr> <td style="padding: 5px;">Sealing method</td><td style="padding: 5px;">Plastic mold</td></tr> <tr> <td style="padding: 5px;">Mounting height</td><td style="padding: 5px;">1.70 mm MAX</td></tr> <tr> <td style="padding: 5px;">Weight</td><td style="padding: 5px;">0.32 g</td></tr> <tr> <td style="padding: 5px;">Code (Reference)</td><td style="padding: 5px;">P-LFQFP64-10x10-0.50</td></tr> </table>	Lead pitch	0.50 mm	Package width × package length	10.0 × 10.0 mm	Lead shape	Gullwing	Sealing method	Plastic mold	Mounting height	1.70 mm MAX	Weight	0.32 g	Code (Reference)	P-LFQFP64-10x10-0.50
Lead pitch	0.50 mm														
Package width × package length	10.0 × 10.0 mm														
Lead shape	Gullwing														
Sealing method	Plastic mold														
Mounting height	1.70 mm MAX														
Weight	0.32 g														
Code (Reference)	P-LFQFP64-10x10-0.50														



18. Major Changes

Spansion Publication Number: MB96620_DS704-00008

Page	Section	Change Results
Revision 2.0		
4	Features	Changed the description of "External Interrupts" Interrupt mask and pending bit per channel → Interrupt mask bit per channel
25 to 28	Handling Precautions	Added a section
36	Electrical Characteristics 3. Dc Characteristics (1) Current Rating	Changed the Conditions for I_{CCSRCH} $CLKS1/2 = CLKB = CLKP1/2 = CLKRC = 2MHz$, → $CLKS1/2 = CLKP1/2 = CLKRC = 2MHz$, Changed the Conditions for I_{CCSRCL} $CLKS1/2 = CLKB = CLKP1/2 = CLKRC = 100kHz$ → $CLKS1/2 = CLKP1/2 = CLKRC = 100kHz$
37		Changed the Conditions for I_{CCTPLL} PLL Timer mode with $CLKP1 = 32MHz$ → PLL Timer mode with $CLKPLL = 32MHz$ Changed the Value of "Power supply current in Timer modes" I_{CCTPLL} Typ: $2480\mu A \rightarrow 1800\mu A$ ($T_A = +25^\circ C$) Max: $2710\mu A \rightarrow 2245\mu A$ ($T_A = +25^\circ C$) Max: $3985\mu A \rightarrow 3165\mu A$ ($T_A = +105^\circ C$) Max: $4830\mu A \rightarrow 3975\mu A$ ($T_A = +125^\circ C$)
38		Changed the Conditions for I_{CCTRCL} RC Timer mode with $CLKRC = 100kHz$, $SMCR:LPMSS = 0$ ($CLKPLL$, $CLKMC$ and $CLKSC$ stopped) → RC Timer mode with $CLKRC = 100kHz$ ($CLKPLL$, $CLKMC$ and $CLKSC$ stopped)
49	4. Ac Characteristics (10) I ² C Timing	Added parameter, "Noise filter" and an annotation *5 for it Added t_{SP} to the figure
51	5. A/D Converter (2) Accuracy And Setting Of The A/D Converter Sampling Time	Deleted the unit "[Min]" from approximation formula of Sampling time
56	7. Flash Memory Write/Erase Characteristics	Changed the condition $(V_{CC} = AV_{CC} = 2.7V \text{ to } 5.5V, VD=1.8V \pm 0.15V, V_{SS} = AV_{SS} = 0V, T_A = -40^\circ C \text{ to } +125^\circ C)$ → $(V_{CC} = AV_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = AV_{SS} = 0V, T_A = -40^\circ C \text{ to } +125^\circ C)$